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PRODUCT CHANGE NOTIFICATION

PCN: PCN171504A

Date: September 07, 2017

Subject: Addendum to PCN171504 – Qualification of Sumitomo G700LS Mold Compound and Roughened NiPdAu Leadframe for 20 and 28-Lead SSOP Automotive Packages Assembled at Amkor Philippines 1

To: JAMIE PEDERSON DIGIKEY digiKey.supplierInfo@digikey.com

Change Type: Major

Description of Change:

The purpose of this addendum is to communicate the additional 2nd Bill of Materials which is also affected by PCN171504. The 2nd Bill of Materials is associated with the 20 and 28-Lead SSOP automotive packages assembled at Amkor Philippines 1.

Cypress announced the qualification of Sumitomo G700LS mold compound and Roughened NiPdAu leadframe for 20 and 28-Lead SSOP Automotive packages assembled at Amkor Philippines 1. The qualification will enable Cypress to meet our customers' stringent quality and reliability requirements in our effort to continually provide world-class services. 20 and 28-Lead SSOP packages assembled at Amkor Philippines 1 (P1) will use the following Bill of Materials (BOM).

1st Bill of Materials (BOM):

Material	Amkor P1 Current BOM	Amkor P1 New BOM
Mold Compound	Sumitomo 6600H	Sumitomo G700LS
Lead Finish	Pure Sn (Smooth surface)	NiPdAu (Roughened surface)
Die Attach Epoxy	Ablestik 8290	Ablestik 8290
Bond Wire	Gold wire 1.0 mil	Gold wire 1.0 mil

2nd Bill of Materials (BOM):

Material	Amkor P1 Current BOM	Amkor P1 New BOM
Mold Compound	Sumitomo G600	Sumitomo G700LS
Lead Finish	NiPdAu (Smooth surface)	NiPdAu (Roughened surface)
Die Attach Epoxy	Ablestik 8290	Ablestik 8290
Bond Wire	Gold wire 1.0 mil	Gold wire 1.0 mil

There are no changes to ordering part numbers. Product datasheets remain the same and can

be downloaded from Cypress website (www.cypress.com).

Benefit of Change:

The qualification of the new bill of materials allows for an improvement in product reliability and product cycle time.

Affected Part Numbers: 78

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

This change has been qualified through a series of tests identified in the Qualification Test Plan (QTP) Report# 163310. The QTP report can be found in the attachment to this notification or by visiting <u>www.cypress.com</u>, typing the QTP number in the keyword search window.

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please refer to the affected parts list file for a list of affected part numbers with their associated sample ordering part numbers. Samples for products listed below are available. If you require qualification samples, please contact your sales representative as soon as possible, but within 30 days of the date of this PCN.

Approximate Implementation Date:

This change will be implemented upon customer approval and all shipments of the affected part numbers in the attached file will be manufactured with the combination of the BOM shown above.

Anticipated Impact:

Products manufactured are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

There will be no changes to the part number. Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration